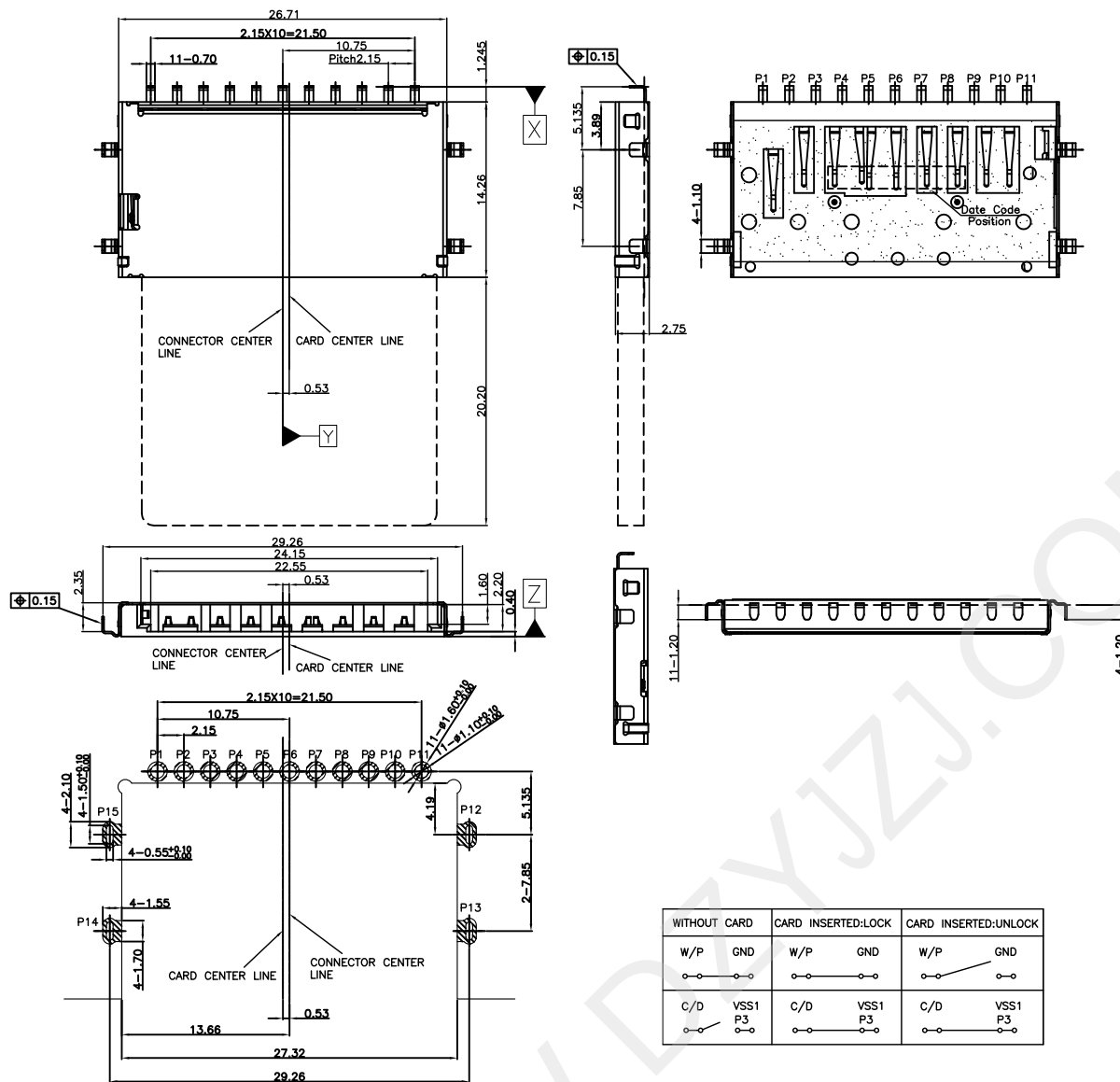
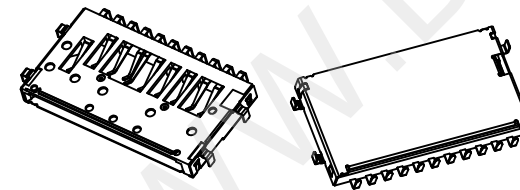




RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)

- PAD AREA
 KEEP OUT AREA
 GND PATTERN ONLY

WITHOUT CARD	CARD INSERTED:LOCK	CARD INSERTED:UNLOCK
W/P GND 	W/P GND 	W/P GND
C/D VSS1 P3 	C/D VSS1 P3 	C/D VSS1 P3



Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		W/P
P12~P15		GND

NOTES :

1.Material:

- 1.1 Insulator:High Temperature Thermoplastic, (LCP,S475),UL Black 94V-0.
- 1.2 Contact: Phosphor Bronze(C5191-EH,T=0.15 $\pm$ 0.03mm)
- 1.3 Shell: SUS304-3/4H,T=0.15 $\pm$ 0.03mm

2 Plating:

- 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area
Plated 80u"min Sn over Ni on solder area
- 2.2 Shell: Plated 50u"min Ni Overall

3.Property:

- 3.1 Current Rating :0.5A AC/DC
- 3.2 Voltage Rating :250VRMS
- 3.3 Dielectric Withstanding Voltage: AC 500V r.m.s.
- 3.4 Insulation Resistance:1000M Ω minimum.
- 3.5 Contact Resistance:100m Ω maximum
- 3.6 Operating Temperature:-25°C~90°C

4. Part Must Comply Taisol HF WD-3-I-091 Specification.

5. Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, IF Use A Metal Mask Less Than 0.15mm Thick.



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD NO PUSH 短体板下DIP 沉板2.35
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC102-SD11-235
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO. DRAW NO: HYC-2509091632
			SHEET NO. 1 OF 1